

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-41. (Cancelled)

42. (Previously Presented) A laminate having a first layer construction of a first inorganic material layer/an insulating layer/a second inorganic material layer or a second layer construction of the inorganic material layer/the first insulating layer, wherein:

at least the first insulating layer has a multi-layer structure including at least a first resin layer and a second resin layer;

the first resin layer has a first etching rate when etched with an alkali-aliphatic amine solution and the second resin layer has a second etching rate when etched with the alkali-aliphatic amine solution; and

a ratio of the first etching rate to the second etching rate is from 4:1 to 1:1.

43. (Cancelled)

44. (Previously Presented) The laminate according to claim 42, wherein the insulating layer comprises a core insulating layer and an adhesive layer provided on both sides of the core insulating layer.

45. (Original) The laminate according to claim 44, wherein the strength of bonding of the adhesive layer to the inorganic material layer and the core insulating layer is at least 300 g/cm.

46. (Previously Presented) The laminate according to claim 44, wherein a thickness ratio of the core insulating layer to each of the adhesive layers is up to 4:1.

47. (Previously Presented) The laminate according to claim 42, wherein at least one of the first resin layer and the second resin layer is formed of a polyimide resin.

48. (Previously Presented) The laminate according to claim 42, wherein each layer of the insulating layer is formed of a polyimide resin.

49. (Cancelled)

50. (Previously Presented) The laminate according to claim 42, wherein the first inorganic material is selected from copper, alloy copper, and stainless steel.

51. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42.

52. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process.

53. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

54. (Previously Presented) A suspension for a hard disk drive, produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

55. (Previously Presented) An insulating film comprising at least a first resin layer and a second resin layer, wherein:

the first resin layer has a first etching rate when etched with an alkali-aliphatic amine solution and the second resin layer has a second etching rate when etched with the alkali-aliphatic amine solution; and

a ratio of the first etching rate to the second etching rate is from 4:1 to 1:1.

56. (Cancelled)

57. (Previously Presented) The insulating film according to claim 55, wherein at least one of the of the first resin layer and the second resin layer is formed of a polyimide resin.

58. (Previously Presented) The insulating film according to claim 55, wherein each layer of the insulating film is formed of a polyimide resin.

59. (Original) A laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

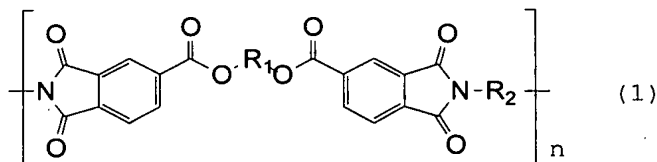
60. (Previously Presented) An electronic circuit component produced by etching a laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

61. (Previously Presented) An electronic circuit component produced by etching a laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process.

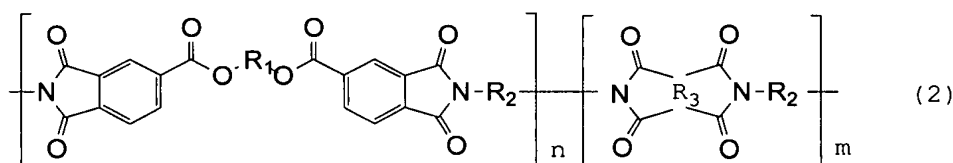
62. (Previously Presented) An electronic circuit component produced by etching a laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.

63. (Previously Presented) A suspension for a hard disk drive, produced by etching a laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.

64. (New) The laminate according to claim 42, wherein at least one of the first resin layer and the second resin layer is formed of a polyimide resin which comprises repeating units represented by formula (1) or formula (2):



wherein R₁ and R₂ each represent a divalent organic group and may have a single structure or a combination of two or more structures; and n is an integer of two or more,



wherein R₁ and R₂ each represent a divalent organic group and may have a single structure or a combination of two or more structures; R₃ represents at least one acid dianhydride selected from the group consisting of diphenylsulfone-2,3,3',4'-tetracarboxylic acid dianhydride, diphenylsulfone-2,2',3,3'-tetracarboxylic acid dianhydride, pyromellitic acid dianhydride, benzophenonetetracarboxylic acid dianhydride, 2,3,3',4'-biphenyltetracarboxylic acid dianhydride, 3,3',4,4'-biphenyltetracarboxylic acid dianhydride, 2,3,3',4'-diphenyl ether tetracarboxylic acid dianhydride, 2,3,3',4,4'-diphenyl ether tetracarboxylic acid dianhydride, and 1,4,5,8-naphthalenetetracarboxylic acid dianhydride; and n and m are an integer of two or more.

65. (New) The laminate according to claim 42, wherein the alkali-aliphatic amine solution comprises monoethanol amine.